IEEE

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tau-Metrix, Inc.
2350 Mission College Blvd., #100
Santa Clara, CA 95054
(408) 727-4100
mario.pelella@tau-Metrix.com

Technical Program Chair
Carlos Mazure, SOITEC
Parc Technologique des Fontaines
Crolles Cedex 38109, France
+33 4 76 92 76 65
Carlos.mazure@soitec.fr

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3536 Enclave Trail
Plano, TX 75074
(512) 565-3354
w-xiong2@ti.com

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Kapeldreef 75
3001 Leuven, Belgium
32 16 28 8015
jurczakm@imec.be

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PSE – Batiment B
CH-1015 Lausanne, Switzerland
+41 21 693 89 91
pfazan@z-ram.com

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2009 IEEE INTERNATIONAL SOI CONFERENCE
Crowne Plaza Hotel • Foster City, California
5 – 8 October, 2009

CALL FOR PAPERS

The IEEE Electron Devices Society will sponsor the 35th IEEE International SOI Conference 5 – 8 October, 2009 at Crowne Plaza Foster City in Silicon Valley, California. The technical sessions will be preceded by a one-day Tutorial Short Course on 5 October. The purpose of the Conference is to provide a forum for open discussion in all areas of silicon-on-insulator technologies, their applications and the related infrastructure. A Fundamentals Class on Wednesday afternoon will allow participants to review and understand the basics of SOI devices and circuits. A Rump session on Wednesday evening will encourage attendees to share their opinions and technical expertise on a chosen topic. A Best Paper Award and a Best Student Paper Award will be presented at the conclusion of the Conference.

Previously unpublished papers are solicited in all areas of SOI technology, including:

♦ SOI DEVICE PHYSICS AND MODELING

♦ MANUFACTURABILITY AND PROCESS INTEGRATION OF SOI DEVICES

♦ LOW-POWER SOI TECHNOLOGY AND CIRCUIT DESIGN INFRASTRUCTURE

♦ SOI CIRCUIT APPLICATIONS (HIGH-PERFORMANCE MPU, SRAM, ASIC, HIGH-VOLTAGE, RF, ANALOG, MIXED MODE, ETC.)

♦ SOI DOUBLE & MULTIPLE GATE/VERTICAL CHANNEL STRUCTURES; OTHER NOVEL SOI STRUCTURES

♦ NEW SOI STRUCTURES, CIRCUITS, AND APPLICATIONS (DISPLAYS, MICROACTUATORS, NOVEL MEMORIES, OPTICS, ETC.)

♦ SOI RELIABILIITY ISSUES (HOT-CARRIER EFFECTS, RADIATION EFFECTS, HIGH-TEMPERATURE EFFECTS, ETC.)

♦ MATERIAL SCIENCE/MODIFICATION, SOI CHARACTERIZATION, MANUFACTURE

♦ SUBSTRATE ENGINEERING (III-V ADVANCED SUBSTRATES, HYBRID SI AND III-V INTEGRATION)

♦ SOI SENSORS, MEMS, AND RFIDS TECHNOLOGY AND APPLICATIONS

♦ 3D INTEGRATION (IMAGERS, POWER DEVICES, WAFER-TO-WAFER AND DIE TO WAFER 3D INTEGRATION)

SUBMISSION INFORMATION

Prospective authors should prepare a 2-page abstract of their work including illustrations that are suitable for reproduction in the conference proceedings (see instructions on back of this page). A paper with more than two pages will be automatically returned. Indicate a preference for poster or oral presentation. Submissions will be accepted for review in PDF format only and should be e-mailed to **soipaper@bacminc.com**. If the PDF requirement presents a problem, please contact the conference manager for assistance at **bobbi@bacminc.com** or call (310) 305-7885 between the hours of 8:30 am and 4:30 pm Pacific Time.

DEADLINE INFORMATION

Papers should be e-mailed no later than **1 May, 2009**. Notice of acceptance will be forwarded by **10 July, 2009**. Late papers with exceptional merit will be considered for the Late News Session if submitted on or before **24 August, 2009**. For further information, please contact the conference manager at:

BACM
578 Washington Blvd., #350
Marina del Rey, CA 90292
Phone: (310)305-7885 Fax: (310)305-1038
bobbi@bacminc.com

Preparation of the 2-page abstract (Title – Initial Caps, 1´´ from the top of the page)

J.P. Author and G.E. Co-author (Author(s) – Initial Caps)
ACME Corp., First City, NY (Company information)
Email: Name@workplace.com, Tel: (xxx) xxx-xxxx

This set of instructions is given in the style and format to be used by authors in preparing "camera-ready" abstracts for the 2009 IEEE International SOI Conference. Please follow the instructions listed below. **Note** that a two column format must be used, and a template may be downloaded from **http://www.soiconference.org**

Criteria for selection

Abstract review will be based on QUALITY, ORIGINALITY, and SIGNIFICANCE, and hence the summary should clearly reveal these attributes of the work described.

Size

The total length of the submitted abstract including all text, graphs, tables, charts, drawings and pictures, is **two pages**. The accepted abstracts are published in the conference proceedings as received (Please note that there is no option to submit a three page long version this year). The abstracts must be typed within the frame shown (2 columns of 3.16´´ wide and 0.17´´ spacing by 9´´ tall) which may be used as a template; **the frame must not appear on the summary**.

Margins are 1´´ from the top of the page to the Title, 1´´ from the bottom of the page, and 1´´ left and right margins, for 8.5´´x11´´ paper. The title shall be bold if possible, centered at the top of the page, and followed by the name(s) of the author(s) and their affiliation(s).

The font size/pitch used in the manuscript should be no smaller than 10 point/12 characters per inch. Tables, graphs and figures may be smaller if legible.

Pictures

Half-tone copies of black and white photographs are preferable for reproduction; however, if this is not possible, please understand that the reproduction quality may be degraded.

Cover letter

Please submit an electronic copy of your 2-page abstract along with a separate cover letter (may be the cover email) identifying the contact author, mailing address, telephone number, fax number and e-mail address. **Also identify the presenting author**, and indicate a preference for poster or oral presentation. The conference will accept submissions only in **electronic form** and only in **PDF** format. The PDF file must be emailed as an attachment to the cover letter and sent to the conference manager at **soipaper@bacminc.com**. For additional information on PDF requirements (fonts, password, compression, etc.), please refer to the IEEE guidelines located on the conference website in the download section.

Notification

Please submit your summary early, but no later than 1 May 2009. You will be notified of the receipt of your summary. You will also be notified by 10 July, 2009 whether your paper is accepted for the conference. If your paper is accepted, you will be requested to complete an IEEE copyright form. Please be sure to have sponsor approval if required.

Authors are encouraged to use and electronic format for their presentation and are requested to submit the file of their talk no later than one week before the conference to **bobbi@bacminc.com**; a confirmation email will be sent to acknowledge a submission was received. Authors of Posters are requested to send a 1 slide only presentation.

Best Paper & Best Poster awards

A Best Paper Award and a new Best Poster Award will be awarded based on the summary submitted as well as the presentation at the conference. Late News papers will not be eligible for awards consideration.